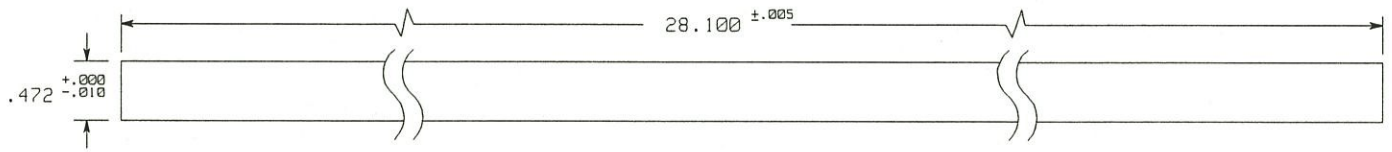
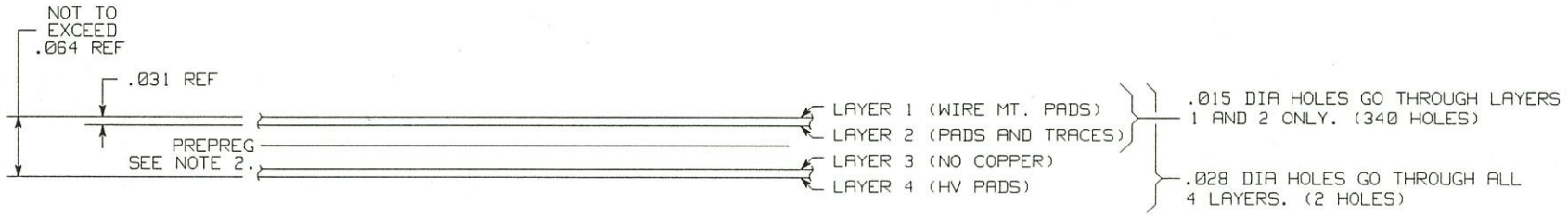
REV.	CHANGES	DRAWN	DATE	CHKD.	DATE

LAYER 1 VIEW





NOTES:

1. BOARD MATERIAL: .031 THICK G10 PER MIL-P-55617 FL-GEN 031C-1/1-A1A (1 OZ. COPPER EACH SIDE). THIS IS A MULTILAYER BOARD (4 LAYERS). TOTAL THICKNESS NOT TO EXCEED .064.
2. PREPREG THICKNESS TO BE DETERMINED BY MANUFACTURER PER IPC-L-109A OR MIL-P-55617.
3. MANUFACTURER MAY NOT PUT ANY IDENTIFICATION NOMENCLATURE ON PRINTED CIRCUIT BOARD.
4. PLEASE NOTE THAT THERE IS NO COPPER ON LAYER 3.
5. DIMENSIONS ARE IN INCHES.
6. BOARD SIZE IS .472 +.000/-.010 X 28.100 +/-.005.
7. REFERENCE DRAWINGS:

24A4502 E-1	a000896e1	HOLE SCHEDULE - SINGLE BOARD
24A4503 E-2	a000896e2	HOLE SCHEDULE - PANEL OF 16 (BLIND VIAS)
24A4503 E-3	a000896e3	HOLE SCHEDULE - PANEL OF 16
24A4503 M-2	a000896m2	BOARD OUTLINE - PANEL OF 16

DIST I:		TITLE	STAR TPC		
DIST II:			INNER SECTOR ELECTRONICS		
DIST III:			GATED GRID WIRE MOUNT BOARD - SINGLE BD.		
SHOWN ON			BOARD OUTLINE - 24A4501 U-1 (A000896U1)		
ACCOUNT NUMBER	8052-24	DRAWN STIRKKINEN	DATE 4/08/94	LAWRENCE BERKELEY LABORATORY	
SERIAL NUMBER		CHECKED	DATE	UNIVERSITY OF CALIFORNIA	
DATE ISSUED	NO. REQD.	APPROVED	DATE	OFFICE OF ELECTRONICS ENGINEERING	
DATE REQD.		ENGINEER JIM HUNTER		FILE NO. a000896m1 / SIZE 2 / DRAWING NO. 24A4502 M-1 / REV.	
DEL. TO		SCALE NONE	E2	SHEET 1 OF 2	